

**Amendment to the Specification:**

Please replace paragraph [0016] with the following amended paragraph:

**[0016]** In an optional step, as shown in Figure 5C, a stiffener 330 may be applied to the backside 324 of the die 320. The stiffener 330 is preferably copper, but may be any material suitable for adding structural rigidity to the die 320. More preferably, the stiffener 330 is a material with a relatively high thermal conductivity, such that it may serve as a heat spreader, allowing greater heat dissipation from the die 320. The stiffener material may be dispensed, such as by a sputtering process, or may be positioned mechanically. For a die 320 with an exemplary thickness between 11-15 mils (~~where one mil is roughly equivalent to 0.025 millimeters~~), the stiffener 330 may be about 5 mils thick, with the thickness varying according to die size as well as thermal and rigidity concerns. In a completed integrated interconnect package, the stiffener 330 may be exposed or concealed, depending on the needs of the particular device.